Preferred Device

## **Dual Common Cathode Schottky Barrier Diodes**

These Schottky barrier diodes are designed for high speed switching applications, circuit protection, and voltage clamping. Extremely low forward voltage reduces conduction loss. Miniature surface mount package is excellent for hand-held and portable applications where space is limited.

- Extremely Fast Switching Speed
- Low Forward Voltage 0.35 V (Typ) @  $I_F = 10 \text{ mA}$
- This is a Pb–Free Device

<b>WAXIMUW RATINGS</b> (1) = 125°C unless otherwise noted)					
Rating	Symbol	Value	Unit		
Reverse Voltage	V <sub>R</sub>	30	Volts		
Forward Power Dissipation @ T <sub>A</sub> = 25°C Derate above 25°C	P <sub>F</sub>	190 1.9	mW mW/°C		
Forward Current (DC)	١ <sub>F</sub>	200 Max	mA		
Junction Temperature	TJ	125 Max	°C		
Storage Temperature Range	T <sub>stg</sub>	-55 to +150	°C		
Thermal Resistance Junction-to-Ambient (Note 1)	$R_{\theta JA}$	525	°C/W		

#### MAXIMUM RATINGS (T<sub>J</sub> = 125°C unless otherwise noted)

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

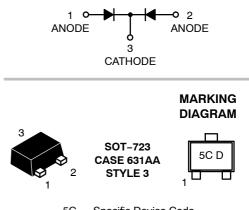
1. FR-5 board with minimum mounting pad.



## **ON Semiconductor®**

http://onsemi.com

## 30 V DUAL COMMON CATHODE SCHOTTKY BARRIER DIODES



5C = Specific Device Code D = Date Code

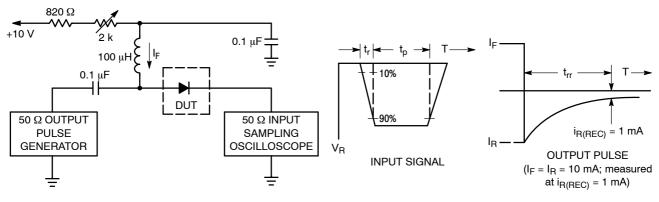
### **ORDERING INFORMATION**

Device	Package	Shipping <sup>†</sup>
NSR30CM3T5G	SOT–723 (Pb–Free)	8000/Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

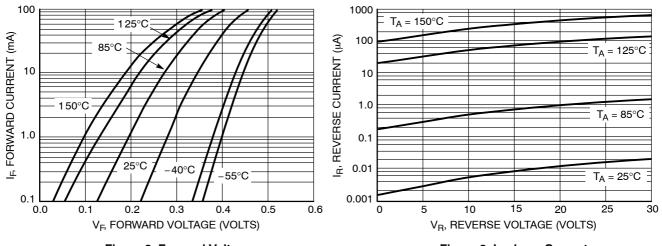
**Preferred** devices are recommended choices for future use and best overall value.

Characteristic	Symbol	Min	Тур	Max	Unit
Reverse Breakdown Voltage (I <sub>R</sub> = 10 μA)	V <sub>(BR)R</sub>	30	-	_	V
Total Capacitance (V <sub>R</sub> = 1.0 V, f = 1.0 MHz)	C <sub>T</sub>	-	7.6	10	pF
Reverse Leakage (V <sub>R</sub> = 25 V)	I <sub>R</sub>	-	0.5	2.0	μΑ
Forward Voltage (I <sub>F</sub> = 0.1 mA)	V <sub>F</sub>	-	0.22	0.24	V
Forward Voltage (I <sub>F</sub> = 30 mA)	V <sub>F</sub>	-	0.41	0.5	V
Forward Voltage (I <sub>F</sub> = 100 mA)	V <sub>F</sub>	-	0.52	0.8	V
Reverse Recovery Time ( $I_F = I_R = 10 \text{ mA}, I_{R(REC)} = 1.0 \text{ mA}, Figure 1$ )	t <sub>rr</sub>	-	-	5.0	ns
Forward Voltage (I <sub>F</sub> = 1.0 mA)	V <sub>F</sub>	-	0.29	0.32	V
Forward Voltage (I <sub>F</sub> = 10 mA)	V <sub>F</sub>	-	0.35	0.40	V
Forward Current (DC)	۱ <sub>F</sub>	-	-	200	mA
Repetitive Peak Forward Current	I <sub>FRM</sub>	_	-	300	mA
Non-Repetitive Peak Forward Current (t < 1.0 s)	I <sub>FSM</sub>	-	-	600	mA



Notes: 1. A 2.0 k $\Omega$  variable resistor adjusted for a Forward Current (I<sub>F</sub>) of 10 mA. 2. Input pulse is adjusted so I<sub>R(peak)</sub> is equal to 10 mA. 3. t<sub>p</sub> » t<sub>rr</sub>





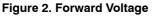


Figure 3. Leakage Current

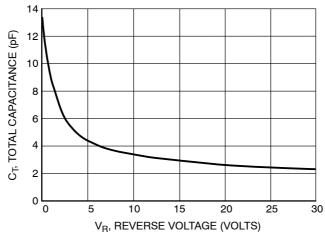


Figure 4. Total Capacitance

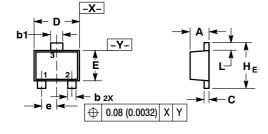
#### PACKAGE DIMENSIONS

SOT-723 CASE 631AA-01 ISSUE B

NOTES:

- 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- 2. CONTROLLING DIMENSION: MILLIMETERS.
- 3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL
- 4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS.

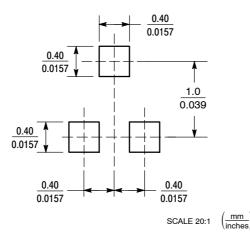
	МІ	MILLIMETERS INCHES				
DIM	MIN	NOM	MAX	MIN	NOM	MAX
Α	0.45	0.50	0.55	0.018	0.020	0.022
b	0.15	0.21	0.27	0.0059	0.0083	0.0106
b1	0.25	0.31	0.37	0.010	0.012	0.015
С	0.07	0.12	0.17	0.0028	0.0047	0.0067
D	1.15	1.20	1.25	0.045	0.047	0.049
E	0.75	0.80	0.85	0.03	0.032	0.034
е	0.40 BSC			C	.016 BS	С
ΗE	1.15	1.20	1.25	0.045	0.047	0.049
L	0.15	0.20	0.25	0.0059	0.0079	0.0098





3. CATHODE

#### SOLDERING FOOTPRINT\*



\*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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